super-PFC/PSR[™] Controller for LED Lighting

FEATURES

- super-PFC/PSR[™] Control Supports Both Primary Side Regulation (PSR) and Secondary Side Regulation (SSR)
- Pin Compatible with Popular PFC Controllers
- ◆ THD<10[®] using *min*-THD[™] Technique
- Built-in AC Line and Load Compensation for High Precision LED Output Current
- Highly Linear Analog Multiplier with "Frequency Adjusting" for High PF
- ♦ Max. 90KHz Frequency Clamping for EMI
- ◆ LED Open/Short Protection
- Burst Mode Control @ Light Loading
- Trimmed 1.5% Internal Voltage Reference
- Very Low Startup Current
- Under Voltage Lockout with 8V Hysteresis
- Built-in Soft Start
- Clear External EA Feedback Network before Power On
- Cycle-by-Cycle Current Limiting
- Built-in Leading Edge Blanking (LEB)
- VCC Over Voltage Protection (OVP)
- Audio Noise Free Operation
- 10V to 32V Wide Range of VCC Voltage
- 500mA Drive Capability

APPLICATIONS

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- LED Lighting Application
- Single Stage High PF Flyback AC/DC SMPS

GENERAL DESCRIPTION

SFL900 is a high performance, high power factor flyback PWM controller special for LED lighting applications. The IC adopts unique **super-PFC/PSRTM** which can support both PSR and SSR applications.

SFL900 is pin compatible with mainstream PFC controllers such as XX6561/6562, XX7527, etc. SFL900 also integrates proprietary **min-THD**TM, technique, which can achieve less than 10% THD for universal line input.

SFL900 has built-in *Load CC Compensation* and *AC Line CC Compensation* function, which can further increase LED output CQ accuracy. The IC has Max. 90KHz Frequency Clamping function and soft totem pole Gate driver to improve system conduction and radiation EMI. The IC will Clear External EA Feedback Network before IC power on, which can reduces startup LED current spike. The IC also has Soft Start control during power on period.

In SFL900, the proprietary "Frequency Adjusting" can help to improve THD performance, while ensures audio noise free operation. SFL900 integrates functions and protections of Under

SFL900 integrates functions and protections of Under Voltage Lockout (UVLO), LED Open/Short Protection, VCC Over Voltage Protection (OVP), Load Over Voltage Protection (Load OVP), Soft Start, Cycle-bycycle Current Limiting (OCP), Burst Mode Control @ Light Loading, GD Clamping, VCC Clamping, etc. SFL900 is available in SOP-8 and DIP-8 packages.







TYPICAL APPLICATION (SSR Application)



Ordering Information

Part Number	Top Mark	Package		Tape & Reel
SFL900SG	SFL900SG	SOP8	Green	
SFL900SGT	SFL900SG	SOP8	Green	Yes
SFL900DP	SFL900DP	DIP8	RoHS	



Marking Information



Pin Description

Pin Name	I/O	Description
FB	Ι	Inverting input of the error amplifier. Before power on, this pin is internally
		shorted to COMP pin to clear external feedback network.
COMP	0	Output of the error amplifier. A feedback network is placed between this
		pin and pin 1. In PSR application, the feedback network can be a
		capacitor. The voltage of COMP and pin CS generates PWM duty cycle.
MULT		Input to the multiplier stage. This pin is connected to the rectified mains
(voltage via a resistor divider and provides the sinusoidal reference to the
)	current loop.
CS	Ι	Current sense input pin.
DEM	I	Demagnetization detection input from auxiliary winding for super-
5		PFC/PSR[™] control. This pin is also used for output over voltage
		protection and output short circuit protection.
GND	Ρ	IC ground pin.
GD	0	Totem-pole gate driver output to drive the external MOSFET.
VCC	Ρ	IC power supply pin.
	Pin Name FB COMP MULT CS DEM GND GD VCC	Pin NameI/OFBICOMPOMULTIMULTIOIOIOIOIOOOOOOOOOOOOOOOOVCCP

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Block Diagram



Absolute Maximum Ratings (Note 1)

Parameter	Value	Unit
VCC DC Supply Voltage	37	V
VCC DC Clamp Current	10	mA
GD pin	20	V
FB, COMP, MULT, CS, voltage range	-0.3 to 7	V
DEM Pin Max. Sink/Source Current	50(source)	mA
	/10(sink)	
Package Thermal Resistance (DIP-8)	90	°C/W
Package Thermal Resistance (SOP-8)	150	°C/W
Maximum Junction Temperature	150	°C
Operating Temperature Range	-40 to 85	°C
Storage Temperature Range	-65 to 150	°C
Lead Temperature (Soldering, 10sec.)	260	°C
ESD Capability, HBM (Human Body Model)	3	kV
ESD Capability, MM (Machine Model)	250	V

Recommended Operation Conditions (Note 2)

Parameter	Value	Unit
Supply Voltage, VCC	10 to 32	V
Operating Ambient Temperature	-40 to 85	°C



ELECTRICAL CHARACTERISTICS

 $(T_A = 25^{\circ}C, VCC = 14.5V \text{ if not otherwise noted})$

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Supply Voltage Section (VCC Pin)						
Ivcc_Startup	VCC Start up Current	VCC=15.5V, Measure		5	15	uA
		current into VCC				
UVLO(ON)	VCC Under Voltage		15.8	16.8	17.8	V
	Lockout Exit (Startup)					
UVLO(OFF)	VCC Under Voltage		8.0	8.8	10	V
	Lockout Enter			-		
UVLO(Hys)	UVLO Hysteresis	UVLO(ON)-UVLO(OFF)		8		
VCC_OVP	VCC Over Voltage		33	35	37	
	Protection trigger	1(1/(CC)) = 5mA	25	27		
VCC_Clamp	Voc Zener Clamp	I(VCC) = 5 mA	35	37	39	
	Operation Current	@70KHz CD=1pE		1	5.5	m۸
LVCC_op		No Switching		3		mΔ
T_VCC_quiet	Soft Start Time	No Switching				mSec
Fror Amplifier	Section (FB and COM	P Pin)			-	moce
	Voltage Feedback		104	100	406	m\/
▼ FBREF	Input Threshold		+3+		400	IIIV
	Line Regulation	10V <vcc<32v< td=""><td></td><td>1</td><td>2</td><td>mV</td></vcc<32v<>		1	2	mV
	Temperature Stability	-40° C <t. <125°c<="" td=""><td></td><td>1</td><td>-</td><td>mV</td></t.>		1	-	mV
△ V _{FB_Temp}	Voltage Coin	Note 2	60	00		dP
	Vollage Galli Unit Coin Bondwidth	Note 3	00	00		
	Source Current		2	1.2	10	mA
Icomp_source	Sink Current	$V_{COMP}=3.6V, V_{FB}=2.4V$	-2	-4.0	-10	mΔ
Vous Clamp II	Unner Clamp Voltage	$V_{COMP}=3.0V$, $V_{FB}=2.0V$	-2	-4.0 5.1		V
V _{COMP} _Clamp_C	COMP under voltage			2.25		V
VCOMP_IIIII_ddity	gate clock is off			2.20		v
Multiplier Sectio	n (MUII T Pin)	× `				
Vmult	Linear Operating	\sim	0~3.5			V
	Range		• • • • •			-
К	Multiplier Gain	$V_{MULT}=1V, V_{COMP}=3.5V$	0.9	1.0	1.1	1/V
ΔVcs/	Output Max. Slope	V_{MULT} =from 0 to 0.5V,		1.8		V/V
ΔVmult		V _{COMP} =Upper Clamp				
	<i>`</i> `	Voltage				
Current Sense S	ection (CS Pin)					
V _{CS} _clamp	Current Sense			1.8		V
	Reference Clamp					
T_blanking	CS Input Leading			250		nSec
	Edge Blanking Time					_
T _D OC	Over Current	GD=1nF		100		nSec
	Detection and Control					
Demagnetization Detection Section (DEM Pin)						
	DEM Comparator			0.0		
	(Negative going edge)			0.2		V
	(Negative going eage)					
VTH_DEM_hys	Comparator			0.1		V
VDEM clamp H	High clamp voltage		54	6	6.6	V
VDFM clamp I	I ow clamp voltage	I(DEM)=-2 5mA	U.T	0	0.0	V
	Output over voltage			3.2		V
	protection threshold			0.2		[•]
	Number of					
NTRUE OVP	subsequent cycles to			2		Cycle
	be true OVP					- ,
V _{TH} Output short	Output Short Circuit			0.7	İ	V
_ · _	Protection Threshold					



	Minimum OFF time	Note 3		34		uSec
				0.4		4000
	Source Current		25		<i>E</i>	A
IDEM_SOUICE	Capability		-2.5		-5	ШA
IDEM cink	Sink Current	Note 2	3			m۸
	Capability	Note 5				ША
Starter and Max Switching Frequency Limitation Section						
Tstart	Start Timer Period		45	55	65	us
f mov	Max switching			00		KH2
isw_inax	frequency			90		INI IZ
Gate Drive Secti	on (GD Pin)					1.
VOL	Output Low Level	lo = 20 mA (sink)			0.5	V
VOH	Output High Level	lo = 20 mA (source)	12			\checkmark
GD_Clamp	Output Clamp Voltage	VCC=24V		16	X	X
	Level					
T_r	Output Rising Time	GD = 1nF		80		nSec
T_f	Output Falling Time	GD = 1nF		50	N	nSec

Note 1. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Note 2. The device is not guaranteed to function outside its operating conditions.

Note 3. Guaranteed by design. sitirst contidential



CHARACTERIZATION PLOTS





SFL900 is a high performance, high power factor flyback PWM controller special for LED lighting applications. The IC adopts unique **super**-**PFC/PSR[™]** which can support both PSR and SSR applications.

 ◆ super-PFC/PSR[™] Support Both Primary Side Regulation (PSR) and Secondary Side Regulation (SSR)

PSR topology requires no secondary feedback circuit (such as TL431, photo-coupler, etc), which reduces system cost greatly. SSR can achieve high accuracy CC (constant current) and CV (constant voltage) performance. Therefore, in small power applications, PSR is the popular topology, while SSR is superior topology in large power applications.

In SFL900, a proprietary **super-PFC/PSR[™]** is adopted, which can support PSR (primary side regulation) and SSR (Secondary side regulation) simultaneously.

min-THD[™] to Achieve Less than 10% THD Performance for Universal Input

In SFL900, a proprietary *min***-THD**TM technique is built in to improve system THD performance. In general, less then 10% system THD can be achieved.

LED Constant Current (CC) Regulation in PSR Application

When used in primary side regulation occasion, SFL900 can accurately control the LED current by the current feedback control loop. The LED mean current can be approximately expressed as:

$$I_{LED}(mA) = \frac{N}{2} \times \frac{400(mV)}{Rcs(\Omega)}$$

In the equation above, N----The turn ratio of primary side winding to secondary side winding

Rcs--- the sensing resistor connected between the MOSFET source to GND.

UVLO (with 8V Hysteresis) and 5uA Startup Current

Fig. shows a typical startup circuit. Before the IC begins switching operation, it consumes only startup current (typically 5uA) and current supplied through the startup resistor Rst charges the VDD hold-up capacitor Cdd. When VDD reaches UVLO turn-on voltage of 16.8V(typical), SFL900 begins switching and the IC current consumed increased to 3mA (typical). The hold-up capacitor Cdd continues to supply VDD before the energy can be delivered from auxiliary winding Na. During this process, VDD must not drop below UVLO turn-off voltage (typical 8.8V). The selection of Rst and Cdd should be a trade off between the power loss and startup time.



• Low Operating Current

The operating current in SFL900 is as small as 3mA (typical). The small operating current results in higher efficiency and reduces the VDD hold-up capacitance requirement.

Error Amplifier (EA)

The inverting input of the EA is compared to an internal reference voltage (400mV,internally trimmed with 1.5% precision) to regulate LED output current. An external loop compensation network is placed between COMP and FB. When COMP voltage is below 2.25V, PWM cycle will stop.

Burst Mode Control @ Light Loading

When the loading is very small, the system enters into burst mode. When VCOMP drops below 2.3V(typical), SFL900 will stop switching and output voltage starts to drop, which causes the VCOMP to rise. Once VFB rises above 2.3V, switching resumes. Burst mode control alternately enables and disables switching, thereby reducing switching loss in standby mode.

Clear External EA Feedback Network

SFL900 features a control that clear the external EA feedback network before IC power on, as shown in Fig.2. This control can ensure the system start up softly by clearing the residue voltage on C1 and reduce the output LED current spike when system does the ON/OFF testing.







Analog Multiplier for Power Factor Correction

The analog multiplier output limits the MOSFET peak current with respect to the AC half wave rectified input voltage. The multiplier in SFL900 has two inputs. One is the error amplifier (EA) output voltage (VCOMP), while the other is VMULT which is obtained by a resistor divider from the rectified line. The multiplier output can be expressed as the following equation:

$$V_{\text{Multiplier}} = 1.0 \times V_{\text{MULT}} \times (V_{\text{COMP}} - 2.5V)$$

The analog multiplier in SFL900 is specially designed to achieve high linearity over a wide dynamic range. The multiplier output is clamped to 1.8V internally.

Frequency Adjusting

In SFL900, a proprietary function of "Frequency adjusting" is integrated. By setting a low frequency clamp which tracks the variation of the AC half wave rectified input voltage, the PFC THD performance can be improved, as shown in Fig.3.



Low Frequency



Leading Edge Blanking (LEB)

Each time the power MOSFET is switched on, a turn-on spike occurs across the sensing resistor. To avoid premature termination of the switching pulse, an internal leading edge blanking circuit is built in. During this blanking period (250ns, typical), the current limiting comparator is disabled and cannot switch off the gate driver. Thus, conventional RC filtering is not necessary and the propagation delay of current limit protection can be minimized.

• Soft Start



SFL900 features an internal 8ms (typical) soft start that slowly increases the threshold of cycle-bycycle current limiting comparator during startup sequence. It helps to prevent transformer saturation and reduce the stress on the secondary diode during startup. Every restart attempt is followed by a soft start activation.

• 3.3us Minimum OFF Time

In SFL900, a minimum OFF time (typically 3.3us) is implemented to suppress ringing when GATE is off. The minimum OFF time is necessary in applications where the transformer has a large leakage inductance, particularly at low output voltages or startup.

90KHz Maximum Frequency Clamping for EMI

In SFL900, the maximum system switching frequency is clamped to 90KHz, which can improve system conduction EMI performance. Therefore, SFL900 is actual a mixed control of TM (Transition Mode, or Boundary Conduction Mode) mode and DCM (Discontinuous Conduction Mode) mode.

Demagnetization Detection

SFL900 can perform demagnetization detection by using an auxiliary winding of the inductor. When the stored energy is fully released to the output, the voltage on DEM goes down. If DEM pin voltage drops below 0.2V, an internal DEM comparator is triggered and a new switching cycle is initiated following the DEM triggering. The power MOSFET is always turned on with zero inductor current such that the turn-on loss and noise can be minimized.

An internal restart timer (55us, typical) is built in to ensure proper start up operation.

The maximum and minimum voltage of DEM pin is internally clamped to 5.8V and 0V respectively.

Built-in Load and AC Line CC Compensation

In conventional PSR system, the output CC (Constant Current) point can vary with output and AC line voltage. In SFL900, the IC has built-in blocks to compensate the variation, as shown in Fig.4. The IC can adjust CC point based on sensed output voltage and AC line input voltage. In this way, CC accuracy can be improved.





Fig.4

Typically, extra external CC compensation circuits are no needed. If a more précised CC point is conventional external compensation needed, network can be added.

Output Over Voltage Protection (Output OVP) / LED String Open Protection

In SFL900, the output OVP is integrated by plateau sampling the auxiliary winding in flyback phase. The threshold voltage for output OVP is 3.2V, as shown in Fig.5.

If the sampled plateau voltage exceeds the OVP threshold (3.2V), an internal counter starts counting subsequent OVP events. If OVP events are detected in successive 2 cycles, the controller assumes a true OVP and it stops all switching . operations. The counter has been added to prevent incorrect OVP detection which might occur during ESD or lightning events. If the output voltage exceeds the OVP threshold less than 2 successive cycles, the internal counter will be cleared and no fault is asserted.

Output OVP is auto-recovery mode protection (mentioned below).



Output Short Circuit Protection / LED String Short Protection

When the output short circuit happens, the positive plateau of auxiliary winding voltage is near zero and DEM voltage is low. If the voltage at DEM pin is lower than a threshold of 0.7V (typical) and lasts for more than 20ms, the IC will shut down and enter into auto-recovery mode protection (as mentioned below).

Pins Floating Protection

In SFL900, if pin floating situation occurs, the IC is designed to have no damage to system.

VCC OVP (Over Voltage Protection)

When VCC voltage is higher than 35V (typical), VCC OVP (Over Voltage Protection) will be triggered in SFL900 and K is a protection of auto recovery mode (as mentioned below).

◆ Auto Recovery Mode Protection As shown in Fig.6, ence a fault condition (VCC OVP) is detected, switching will stop. This will cause VCC to fall because no power is delivered form the auxiliary winding. When VCC falls to UVLO(OFE) (typical 8.8V), the protection is reset and the operating current reduces to the startup current, which causes VCC to rise, as shown in Fig.6. However, if the fault still exists, the system will experience the above mentioned process. If the fault has gone, the system resumes normal operation. In this manner, the auto restart can alternatively enable and disable the switching until the fault condition is disappeared.



Soft Gate Drive

SFL900 has a fast totem-pole gate driver with 500mA capability. Cross conduction has been avoided to minimize heat dissipation, increase efficiency, and enhance reliability. An internal 16V clamp is added for MOSFET gate protection at higher than expected VCC input. A soft driving waveform is implemented to minimize EMI.

PACKAGE MECHANICAL DATA

SOP8 PACKAGE OUTLINE DIMENSIONS



Symbol	🗙 Dimensions I	n Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0.050	0.250	0.002	0.010	
• A2	1.250	1.650	0.049	0.065	
þ	0.310	0.510	0.012	0.020	
с С	0.170	0.250	0.006	0.010	
D	4.700	5.150	0.185	0.203	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270 (BSC)		0.05 (BSC)		
Ĺ	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



DIP8 PACKAGE OUTLINE DIMENSIONS





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